

ABSTRACT

In an electronics packaging system (1) including a printer (3), placing unit (4) and reflow unit (5), a printed wiring board (2) is carried while being kept in upright position. The printed wiring board (2) has solder printed on lands thereof at the same time, electronic parts (10) placed on the lands at the same time, and the electronic parts (10) solder to the lands at the same time. Thus, the system (1) can be designed more compact, and package electronic parts in a shorter time.

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